

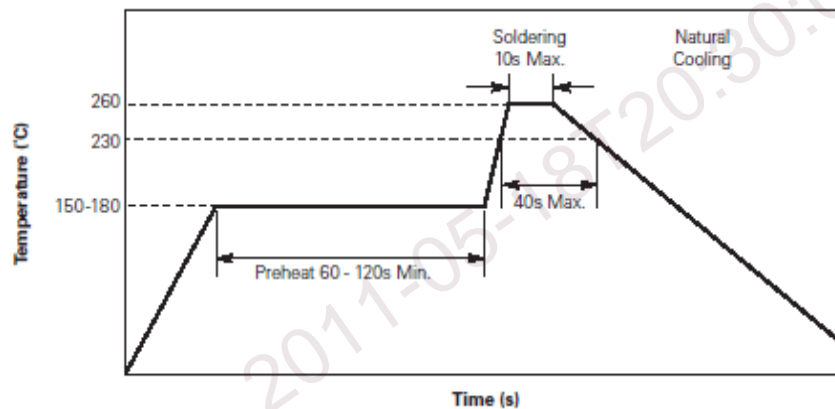
308 Constitution Drive
Menlo Park, CA USA
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Solder Reflow Recommendation:

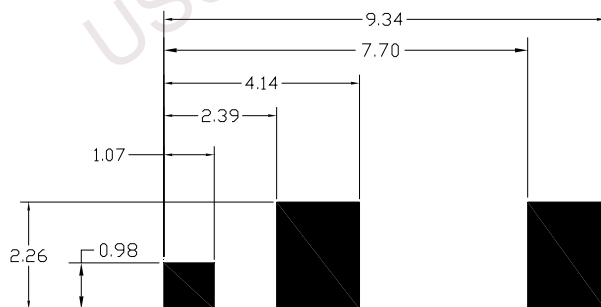
Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average ramp up rate ($T_{S_{MAX}}$ to T_p)	3°C/second max.
Preheat	
• Temperature min. ($T_{S_{MIN}}$)	150°C
• Temperature max. ($T_{S_{MAX}}$)	200°C
• Time ($t_{S_{MIN}}$ to $t_{S_{MAX}}$)	60-180 seconds
Time maintained above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150 seconds
Peak/Classification temperature (T_p)	260°C
Time within 5°C of actual peak temperature	
Time (t_p)	20-40 seconds
Ramp down rate	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

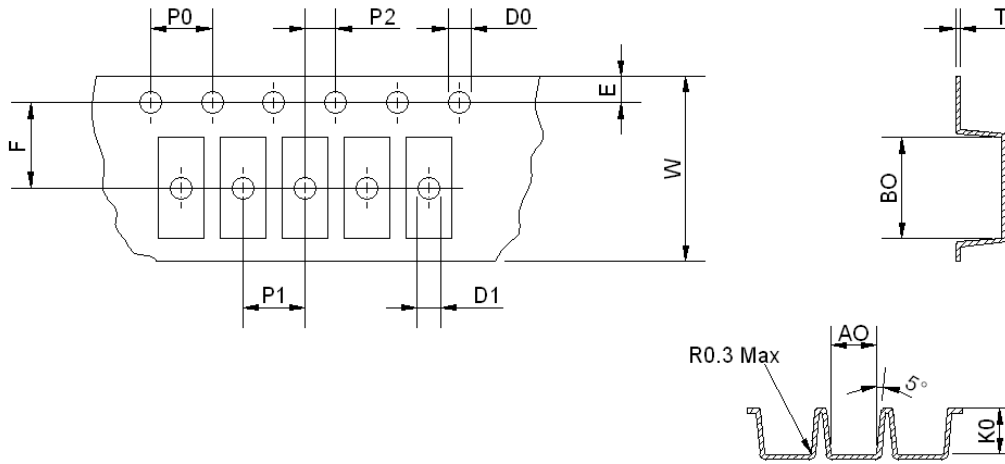
Note: All temperatures refer to topside of the package, measured on the package body surface.



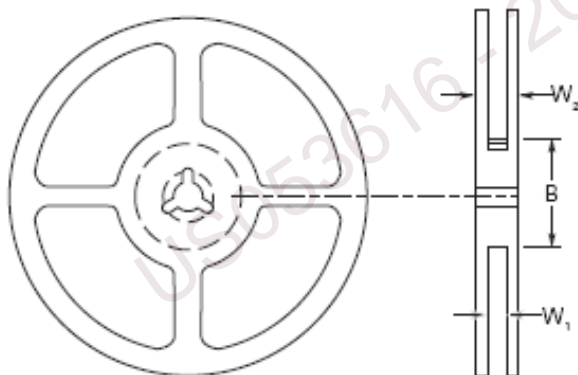
Recommended Pad Layout: mm



Package Information:



	E	F	W	P1	P0	P2
mm	1.75±0.10	11.50±0.10	24.00±0.30	12.00±0.10	4.00±0.10	2.00±0.10
(in)	(0.069±0.004)	(0.453±0.004)	(0.945±0.012)	(0.472±0.004)	(0.157±0.004)	(0.079±0.004)
	D0	D1	T	A0	B0	K0
mm	1.50+0.10/-0.00	1.50±0.10	0.46±0.046	5.70±0.18	12.40±0.18	6.50±0.18
(in)	(0.059+0.004/-0.000)	(0.059±0.004)	(0.018±0.002)	(0.224±0.007)	(0.488±0.007)	(0.256±0.007)



	B	W₁	W₂ Max
mm	102.0 ± 2.0	24	29
(inch)	(4.0 ± 0.079)	(0.945)	(1.14)